

● **General Description**

The TF110P02K combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

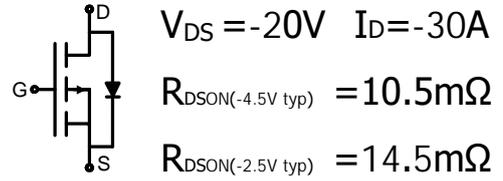
● **Features**

- Advance high cell density Trench technology
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

● **Application**

- Load Switches
- DC/DC
- BLDC Motor driver

● **Product Summary**



● **Ordering Information:**

Part NO.	TF110P02K
Marking1	TF:tuofeng; 110P02K:TF110P02K
Marking2	YY:year code; XX:Week; AA:device code;
Basic ordering unit (pcs)	2500

● **Absolute Maximum Ratings (T<sub>c</sub> =25°C)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current	I <sub>D@TC=25°C</sub>	-30	A
	I <sub>D@TC=75°C</sub>	-21	A
	I <sub>D@TC=100°C</sub>	-18	A
Pulsed Drain Current <sup>①</sup>	I <sub>DM</sub>	-63	A
Total Power Dissipation <sup>②</sup>	P <sub>D</sub>	15	W
Total Power Dissipation(TA=25°C)	P <sub>D@TA=25°C</sub>	1.0	W
Operating Junction Temperature	T <sub>J</sub>	-55 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	°C
Single Pulse Avalanche Energy@L=0.1mH	E <sub>AS</sub>	42	mJ
Avalanche Current@L=0.1mH	I <sub>AS</sub>	-28	A



● **Thermal resistance**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case <sup>②</sup>	R <sub>thJC</sub>	-	-	4.5	° C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	62.5	° C/W
Soldering temperature, wave soldering for 10s	T <sub>sold</sub>	-	-	265	° C

● **Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250uA	-20			V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = -250uA	-0.45	-0.70	-1.00	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1.0	uA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V			±100	nA
Static Drain-source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -15A		10.5	12.0	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -10A		14.5	16.0	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -10A		10		s
Source-drain voltage	V <sub>SD</sub>	I <sub>S</sub> = -10A		0.88	1.28	V

● **Electronic Characteristics**

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -10V f = 1MHz	-	2108	-	pF
Output capacitance	C <sub>oss</sub>		-	275	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	236	-	

● **Gate Charge characteristics**(T<sub>a</sub> = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> = -10V	-	46	-	nC
Gate - Source charge	Q <sub>gs</sub>	I <sub>D</sub> = -10A	-	7.3	-	
Gate - Drain charge	Q <sub>gd</sub>	V <sub>GS</sub> = -4.5V	-	10	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;

Fig.1 Gate-Charge Characteristics

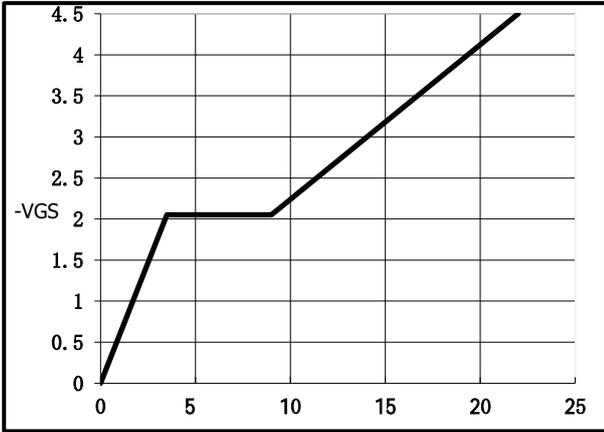


Fig.2 Capacitance Characteristics

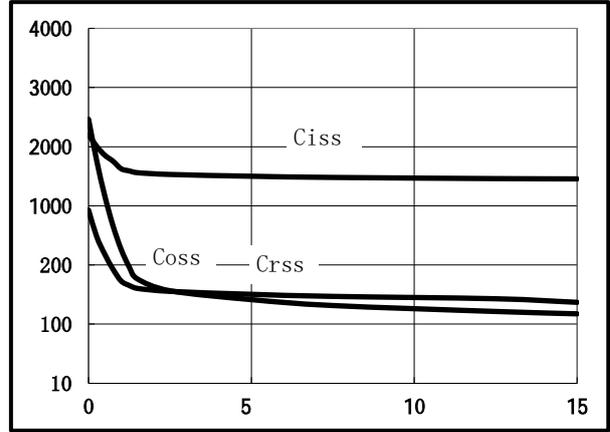


Fig.2 Power Dissipation

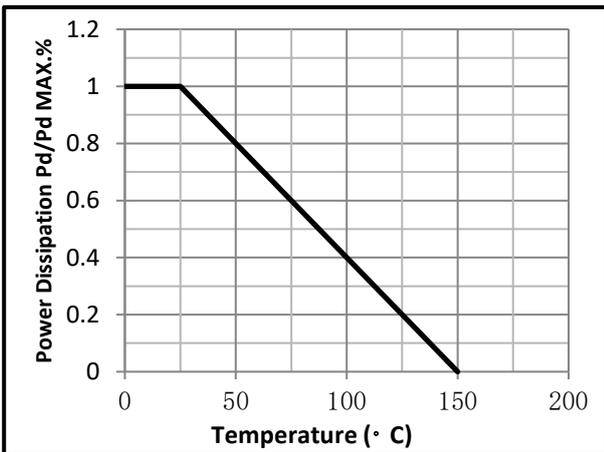


Fig.3 Typical output Characteristics

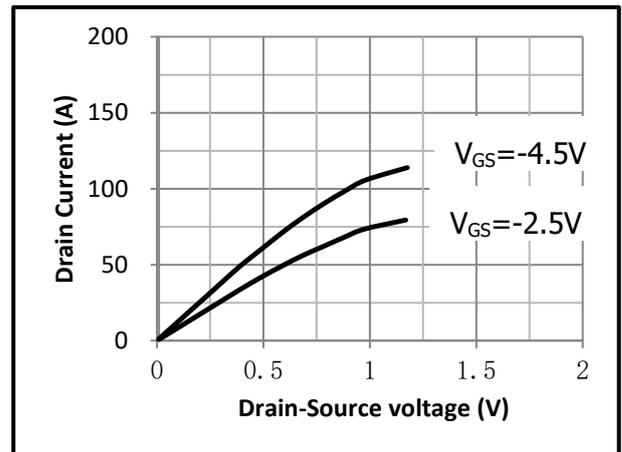


Fig.4 Threshold Voltage V.S Junction Temperature

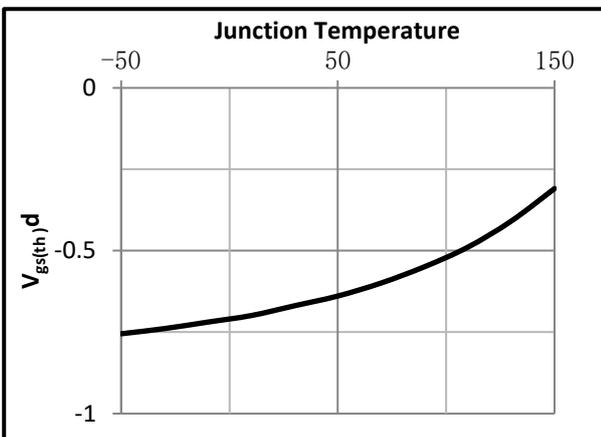


Fig.5 Resistance V.S Drain Current

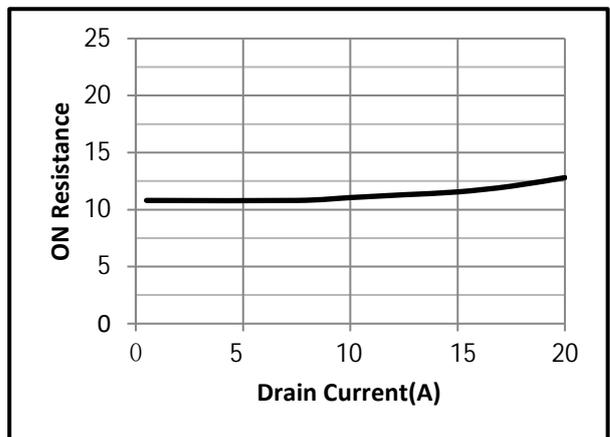


Fig.6 On-Resistance VS Gate Source Voltage

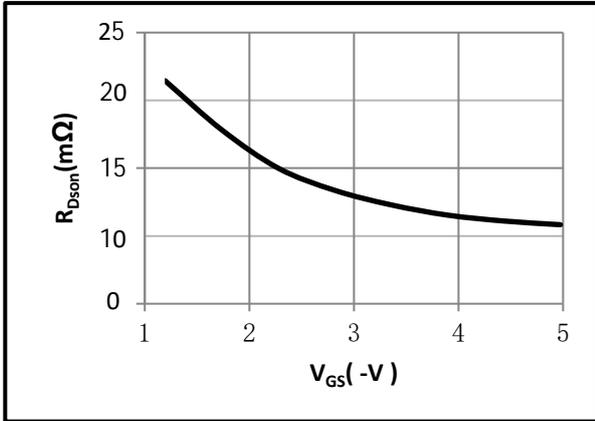


Fig.7 On-Resistance V.S Junction Temperature

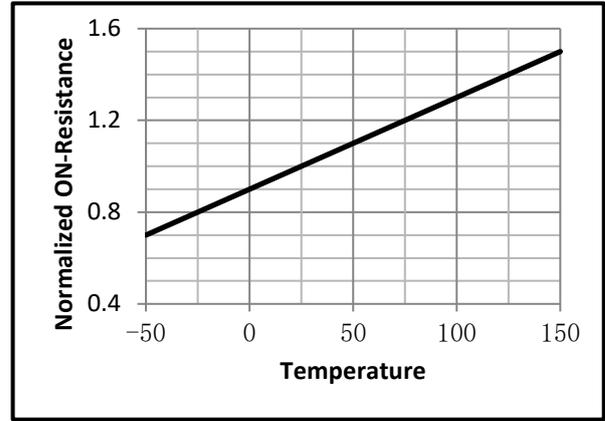


Fig.8 Switching Time Measurement Circuit

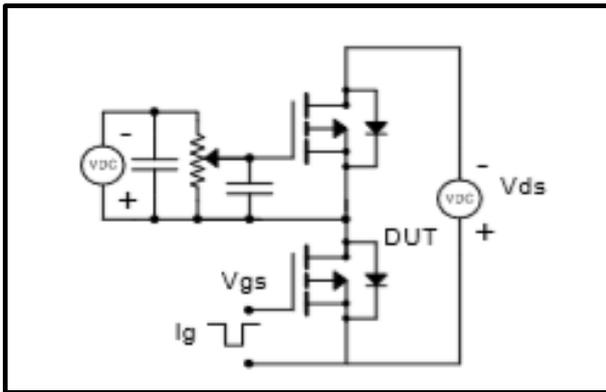


Fig.9 Gate Charge Waveform

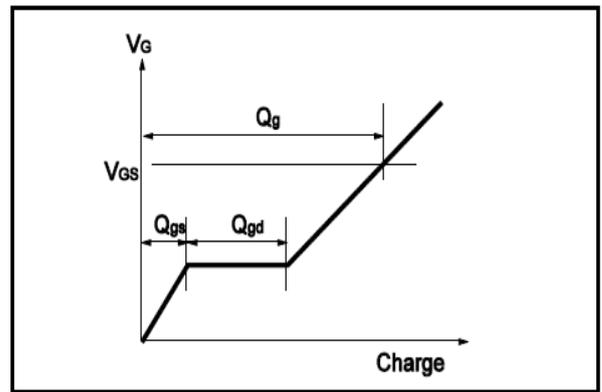


Fig.10 Switching Time Measurement Circuit

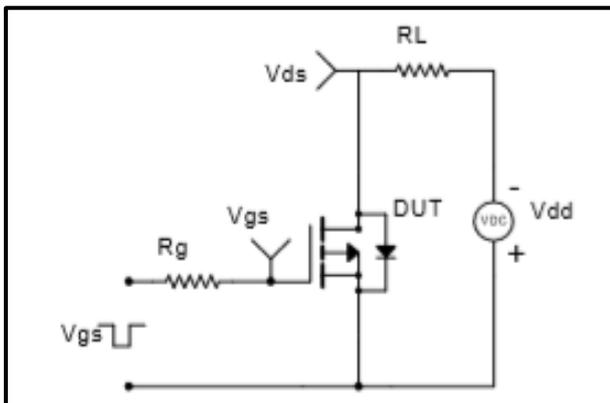
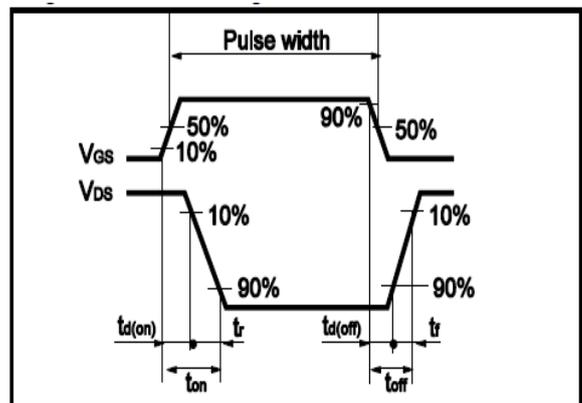
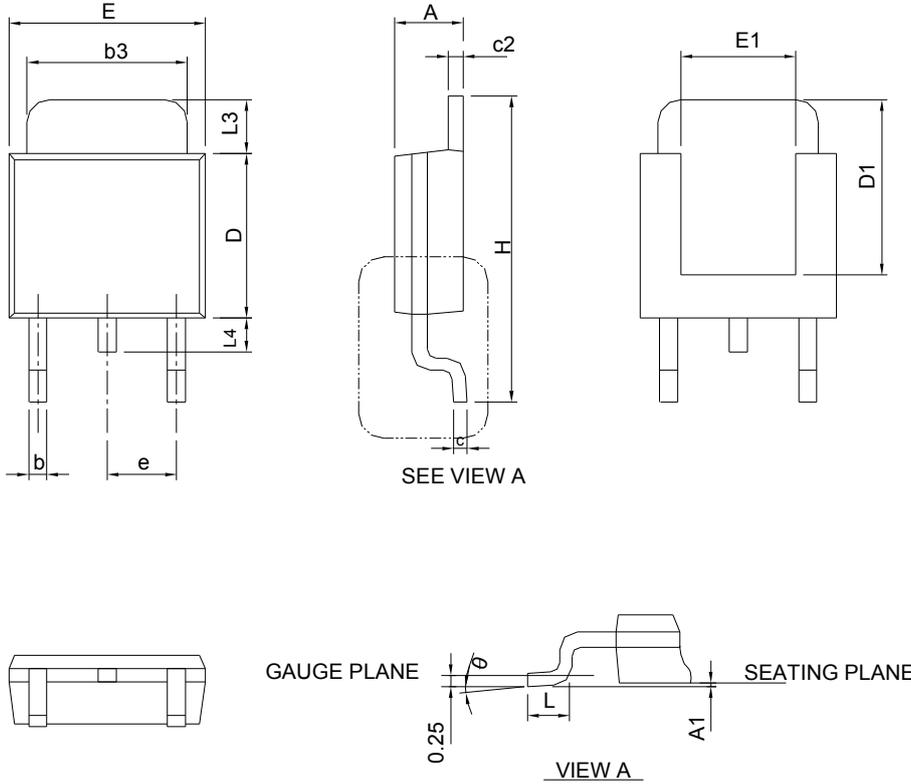


Fig.11 Gate Charge Waveform



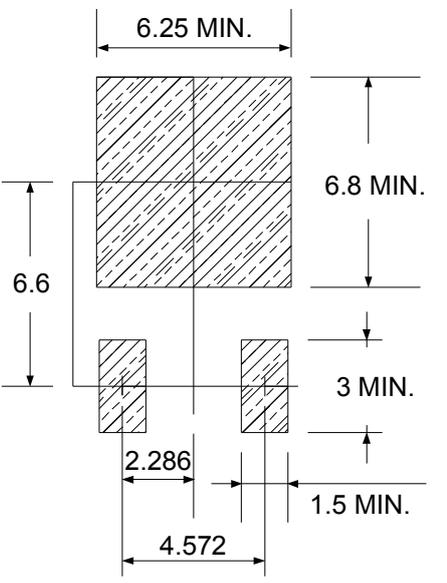
**Package Information**

TO-252



TO-252	TO-252			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

**RECOMMENDED LAND PATTERN**



UNIT: mm